512 MB PC100 / PC133

- u144 Pin Eight Byte Small Outline Dual-In-Line Synchronous DRAM Modules for notebook applications
- Two bank 64M x 64 non-parity module organisation
- suitable for use in PC100 and PC133 applications
- Performance:

		-7	-7.5	-8	
		PC133 2-2-2	PC133 3-3-3	PC100 2-2-2	Units
f_{CK}	Clock frequency (max.)	133	133	100	MHz
t_{AC}	Clock access time CAS latency = 2 & 3	5.4	5.4	6	ns

- Single +3.3V(± 0.3V) power supply
- Programmable $\overline{CAS}$ Latency, Burst Length and Wrap Sequence (Sequential & Interleave)
- Auto Refresh (CBR) and Self Refresh
- Decoupling capacitors mounted on substrate
- All inputs, outputs are LVTTL compatible
- Serial Presence Detect with E^2PROM
- Uses sixteen 256Mbit SDRAM (32Mb x8) components in P-TFBGA packages
- 8196 refresh cycles every 64 ms
- Gold contact pad, JEDEC MO-190 outline dimensions
- This module family is fully pin and functional compatible with the latest INTEL SO-DIMM specification
- **Importante Notice**:
  This SO-DIMM module is based on 256Mbit SDRAM technology and can be used in applications only, where 256Mbit addressing is supported.

This INFINEON module is an industry standard 144 pin 8-byte Synchronous DRAM (SDRAM) Small Outline Dual In-line Memory Modules (SO-DIMM) which is organised as 64Mx64 high speed array in two memory banks designed for use in non-parity applications. These SO-DIMMs use back side protected P-TFBGA package technology. Decoupling capacitors are mounted on the board.

The DIMMs use serial presence detects implemented via a serial E^2PROM using the two pin I^2C protocol. The first 128 bytes are utilized by the DIMM manufacturer and the second 128 bytes are available to the end user.

All INFINEON 144-pin SO-DIMMs provide a high performance, flexible 8-byte interface in a 67,6 mm long footprint.

Product Spectrum

		SDRAMs used	RowAddr.	Bank Select	Column Addr.	Refresh	Period
64M x 64	HYS64V64220GBDL-7-D	16 32Mx8	13	BA0, BA1	10	8k	64 ms
64M x 64	HYS64V64220GBDL-7.5-D	16 32Mx8	13	BA0, BA1	10	8k	64 ms
64M x 64	HYS64V64220GBDL-8-D	16 32Mx8	13	BA0, BA1	10	8k	64 ms

Note: All partnumbers end with a place code (not shown), designating the die revision. Consult factory for current revision. Example: HYS64V64220GBDL-8-D, indicating Rev.D dies are used for SDRAM components.

Card Dimensions

Organisation	PCB-Board	L x H x T [mm]
64M x 64	L-DIM-144-14	67.60 x 29.21 x 3.80

Pin Names

A0-A12	Address Inputs
BA0,BA1	Bank Selects
DQ0 - DQ63	Data Input/Output
$\overline{RAS}$	Row Address Strobe
$\overline{CAS}$	Column Address Strobe
$\overline{WE}$	Read / Write Input
CKE0, CKE1	Clock Enable
CLK0, CLK1	Clock Input
DQMB0 - DQMB7	Data Mask
$\overline{CS0}$, $\overline{CS1}$	Chip Select
VDD	Power (+3.3 Volt)
Vss	Ground
SCL	Clock for Presence Detect
SDA	Serial Data Out for Presence Detect
N.C.	No Connection

Pin Configuration

PIN #	Front Side	PIN #	Back Side		PIN #	Front Side	PIN #	Back Side
1	VSS	2	VSS		73	NC	74	CLK1
3	DQ0	4	DQ32		75	Vss	76	Vss
5	DQ1	6	DQ33		77	NC	78	NC
7	DQ2	8	DQ34		79	NC	80	NC
9	DQ3	10	DQ35		81	VDD	82	VDD
11	VDD	12	VDD		83	DQ16	84	DQ48
13	DQ4	14	DQ36		85	DQ17	86	DQ49
15	DQ5	16	DQ37		87	DQ18	88	DQ50
17	DQ6	18	DQ38		89	DQ19	90	DQ51
19	DQ7	20	DQ39		91	Vss	92	Vss
21	Vss	22	Vss		93	DQ20	94	DQ52
23	DQMB0	24	DQMB4		95	DQ21	96	DQ53
25	DQMB1	26	DQMB5		97	DQ22	98	DQ54
27	VDD	28	VDD		99	DQ23	100	DQ55
29	A0	30	A3		101	VDD	102	VDD
31	A1	32	A4		103	A6	104	A7
33	A2	34	A5		105	A8	106	BA0
35	Vss	36	Vss		107	Vss	108	Vss
37	DQ8	38	DQ40		109	A9	110	BA1
39	DQ9	40	DQ41		111	A10	112	A11
41	DQ10	42	DQ42		113	VDD	114	VDD
43	DQ11	44	DQ43		115	DQMB2	116	DQMB6
45	VDD	46	VDD		117	DQMB3	118	DQMB7
47	DQ12	48	DQ44		119	Vss	120	Vss
49	DQ13	50	DQ45		121	DQ24	122	DQ56
51	DQ14	52	DQ46		123	DQ25	124	DQ57
53	DQ15	54	DQ47		125	DQ26	126	DQ58
55	Vss	56	Vss		127	DQ27	128	DQ59
57	NC	58	NC		129	VDD	130	VDD
59	NC	60	NC		131	DQ28	132	DQ60
61	CLK0	62	CKE0		133	DQ29	134	DQ61
63	VDD	64	VDD		135	DQ30	136	DQ62
65	RAS	66	CAS		137	DQ31	138	DQ63
67	WE	68	CKE1		139	Vss	140	Vss
69	$\overline{CS0}$	70	A12		141	SDA	142	SCL
71	CS1	72	(A13)		143	VDD	144	VDD

Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input / Output voltage relative to V_{SS}	V_{IN}, V_{OUT}	– 1.0	4.6	V
Power supply voltage on V_{DD}	V_{DD}	– 1.0	4.6	V
Storage temperature range	T_{STG}	-55	+125	°C
Power dissipation	P_D	–	16	W
Data out current (short circuit)	I_{OS}	–	50	mA

Permanent device damage may occur if “Absolute Maximum Ratings” are exceeded.
Functional operation should be restricted to recommended operation conditions.
Exposure to higher than recommended voltage for extended periods of time affect device reliability

DC Characteristics

T_A = 0 to 70 °C; V_{SS} = 0 V; V_{DD} = 3.3 V ± 0.3 V

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input high voltage	V_{IH}	2.0	VDD+0.3	V
Input low voltage	V_{IL}	– 0.5	0.8	V
Output high voltage (I_{OUT} = – 4.0 mA)	V_{OH}	2.4	–	V
Output low voltage (I_{OUT} = 4.0 mA)	V_{OL}	–	0.4	V
Input leakage current, any input (0 V < V_{IN} < 3.6 V, all other inputs = 0 V)	$I_{I(L)}$	– 20	20	µA
Output leakage current (DQ is disabled, 0 V < V_{OUT} < V_{DD})	$I_{O(L)}$	– 20	20	µA

Capacitance

T_A = 0 to 70 °C; V_{DD} = 3.3 V ± 0.3 V, f = 1 MHz

Parameter	Symbol	Limit Values	Unit
		64M x 64 max.	
Input capacitance (A0 to A11, BA0, BA1)	C_{I1}	85	pF
Input capacitance ($\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$)	C_{I2}	85	pF
Input Capacitance (CLK0, CLK1)	C_{I3}	70	pF
Input capacitance (CS0, CS1)	C_{I4}	60	pF
Input capacitance (DQMB0-DQMB7)	C_{I5}	15	pF
Input capacitance (CKE0, CKE1)	C_{I6}	50	pF
Input / Output capacitance (DQ0-DQ63)	C_{IO}	18	pF
Input Capacitance (SCL,SA0-2)	C_{sc}	8	pF
Input/Output Capacitance (SDA)	C_{sd}	10	pF

Operating Currents per memory bank

(T_A = 0 to 70°C, V_{DD} = 3.3V ± 0.3V)

(Recommended Operating Conditions unless otherwise noted)

Parameter & Test Condition		Symb.	64Mx64 512Mbyte			Note
			PC133	PC100		
OPERATING CURRENT trc=trcmin., All banks operated in random access, all banks operated in ping-pong manner		ICC1	1840	1360	mA	1, 2
PRECHARGE STANDBY CURRENT in Power Down Mode $\overline{CS}$ =VIH (min.), CKE<=Vil(max)	tck = min.	ICC2P	16	16	mA	1
PRECHARGE STANDBY CURRENT in Non-Power Down Mode $\overline{CS}$ = VIH (min.), CKE>=Vih(min)	tck = min.	ICC2N	320	240	mA	1
NO OPERATING CURRENT tck = min., $\overline{CS}$ = VIH(min), active state (max. 4 banks)	CKE>=VIH(min.)	ICC3N	400	360	mA	1
	CKE<=VIL(max.)	ICC3P	80	80	mA	1
BURST OPERATING CURRENT tck = min., Read command cycling		ICC4	1200	800	mA	1, 2
AUTO REFRESH CURRENT tck = min., trc = trcmin. Auto Refresh command cycling		ICC5	1920	1760	mA	1
SELF REFRESH CURRENT Self Refresh Mode, CKE=0.2V tck =infinity		ICC6	14	14	mA	1

Notes:

1. These parameters depend on the cycle rate. These values are measured at 133 MHz operation frequency for PC133 and at 100MHz for PC100 modules. Input signals are changed once during tck, excepts for ICC6 and for standby currents when tck=infinity.
2. These parameters are measured with continuous data stream during read access and all DQ toggling. CL=3 and BL=4 is assumed and the data-out current is excluded.

AC Characteristics 9)10)
T_A = 0 to 70 °C; V_{SS} = 0 V; V_{DD}, V_{DDQ} = 3.3 V ± 0.3 V, tT = 1 ns
T_A = 0 to 70 °C; V_{SS} = 0 V; V_{DD} = 3.3 V ± 0.3 V, t_T = 1 ns

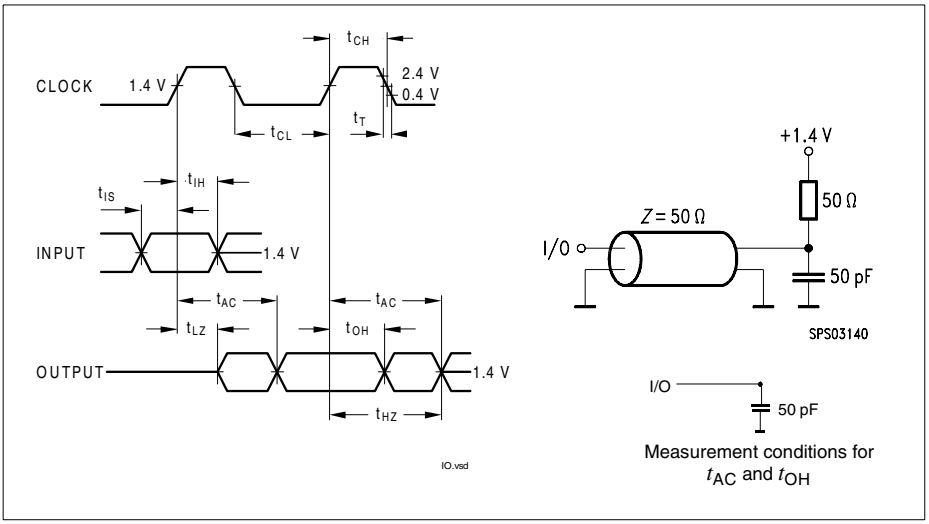
Parameter	Symbol	Limit Values						Unit	
		-7 PC133-222		-7.5 PC133-333		-8 PC100-222			
		min.	max.	min.	max.	min.	max.		
Clock and Clock Enable									
Clock Cycle Time									
CAS Latency = 3	t_{CK}	7	–	7.5	–	8	–	ns	
CAS Latency = 2		7.5	–	10	–	10	–	ns	
Clock Frequency									
CAS Latency = 3	t_{CK}	–	143	–	133	–	125	MHz	
CAS Latency = 2		–	133	–	100	–	100	MHz	
Access Time from Clock									
CAS Latency = 3	t_{AC}	–	5.4	–	5.4	–	6	ns	2, 3, 6
CAS Latency = 2		–	5.4	–	6	–	6	ns	
Clock High Pulse Width	t_{CH}	2.5	–	2.5	–	3	–	ns	
Clock Low Pulse Width	t_{CL}	2.5	–	2.5	–	3	–	ns	
Transition time	t_T	0.3	1.2	0.3	1.2	0.5	10	ns	
Setup and Hold Times									
Input Setup Time	t_{IS}	1.5	–	1.5	–	2	–	ns	4
Input Hold Time	t_{IH}	0.8	–	0.8	–	1	–	ns	4
CKE Setup Time	t_{CKS}	1.5	–	1.5	–	2	–	ns	4
CKE Hold Time	t_{CKH}	0.8	–	0.8	–	1	–	ns	4
Mode Register Set-up to Active delay	t_{RSC}	2	–	2	–	2	–	CLK	
Power Down Mode Entry Time	t_{SB}	0	7	0	7.5	0	8	ns	
Common Parameters									
Row to Column Delay Time	t_{RCD}	15	–	20	–	20	–	ns	5
Row Precharge Time	t_{RP}	15	–	20	–	20	–	ns	5

AC Characteristics 9)10)
T_A = 0 to 70 °C; V_{SS} = 0 V; V_{DD}, V_{DDQ} = 3.3 V ± 0.3 V, tT = 1 ns
T_A = 0 to 70 °C; V_{SS} = 0 V; V_{DD} = 3.3 V ± 0.3 V, t_T = 1 ns

Parameter	Symbol	Limit Values						Unit	
		-7 PC133-222		-7.5 PC133-333		-8 PC100-222			
		min.	max.	min.	max.	min.	max.		
Row Active Time	t_{RAS}	37	100k	45	100k	48	100k	ns	5
Row Cycle Time	t_{RC}	60	–	67	–	70	–	ns	5
Row Cycle Time during Auto Refresh	t_{RFC}	63		67		70		ns	
Activate(a) to Activate(b) Command period	t_{RRD}	14	–	15	–	16	–	ns	5
$\overline{CAS}$(a) to $\overline{CAS}$(b) Command period	t_{CCD}	1	–	1	–	1	–	CLK	
Refresh Cycle									
Refresh Period (8192 cycles)	t_{REF}	–	64	–	64	–	64	ms	
Self Refresh Exit Time	t_{SREX}	1	–	1	–	1		CLK	
Read Cycle									
Data Out Hold Time	t_{OH}	3	–	3	–	3	–	ns	2, 6
Data Out to Low Impedance Time	t_{LZ}	0	–	0	–	0	–	ns	
Data Out to High Impedance Time	t_{HZ}	3	7	3	7	3	8	ns	
DQM Data Out Disable Latency	t_{DQZ}	–	2	–	2	–	2	CLK	
Write Cycle									
Last Data Input to Precharge (Write without AutoPrecharge)	t_{WR}	14	–	15	–	15	–	ns	7
Last Data Input to Activate (Write with AutoPrecharge)	$t_{DAL,min}$							CLK	8
DQM Write Mask Latency	t_{DQW}	0	–	0	–	0	–	CLK	

Notes

1. For proper power-up see the operation section of the component sheet.
2. AC timing tests for LV-TTL versions have V_{IL} = 0.4 V and V_{IH} = 2.4 V with the timing referenced to the 1.4 V crossover point. The transition time is measured between V_{IH} and V_{IL}. All AC measurements assume t_T = 1 ns with the AC output load circuit shown in figure below. Specified t_{AC} and t_{OH} parameters are measured with a 50 pF only, without any resistive termination and with an input signal of 1V / ns edge rate between 0.8 V and 2.0 V.



3. If clock rising time is longer than 1 ns, a time (t_T/2 – 0.5) ns has to be added to this parameter.
4. If t_T is longer than 1 ns, a time (t_T – 1) ns has to be added to this parameter.
5. These parameter account for the number of clock cycles and depend on the operating frequency of the clock, as follows: the number of clock cycles = specified value of timing period (counted in fractions as a whole number)
6. Access time from clock t_{AC} is 4.6 ns for PC133 components with no termination and 0 pF load, Data out hold time t_{OH} is 1.8 ns for PC133 components with no termination and 0 pF load.
7. It is recommended to use two clock cycles between the last data-in and the precharge command in case of a write command without Auto-Precharge. One clock cycle between the last data-in and the precharge command is also supported, but restricted to cycle times tck greater or equal the specified twr value, where tck is equal to the actual system clock time
8. When a Write command with AutoPrecharge has been issued, a time of tdal(min) has be fullfilled before the next Activate Command can be applied. For each of the terms, if not already an integer, round up to the next highest integer. tck is equal to the actual system clock time.
9. All AC characteristics shown are for SDRAM components. An initial pause of 100µs is required after power-up, then a Precharge All Banks command must be given followed by 8 Auto Refresh (CBR) cycles before the Mode Register Set Operation can begin.
10. AC timing tests have V_{il} = 0.4 V and V_{ih} = 2.4 V with the timing referenced to the 1.4 V crossover point. The transition time is measured between V_{ih} and V_{il}. All AC measurements assume t_T=1ns

with the AC output load circuit shown.Specified tac and toh parameters are measured with a 50pF only, without any resistive termination and with a input signal of 1V / ns edge rate between 0.8V and 2.0 V.

Serial Presence Detects

A serial presence detect storage device - E^2PROM - is assembled onto the module. Information about the module configuration, speed, etc. is written into the E^2PROM device during module production using a serial presence detect protocol (I^2C synchronous 2-wire bus)

SPD-Table:

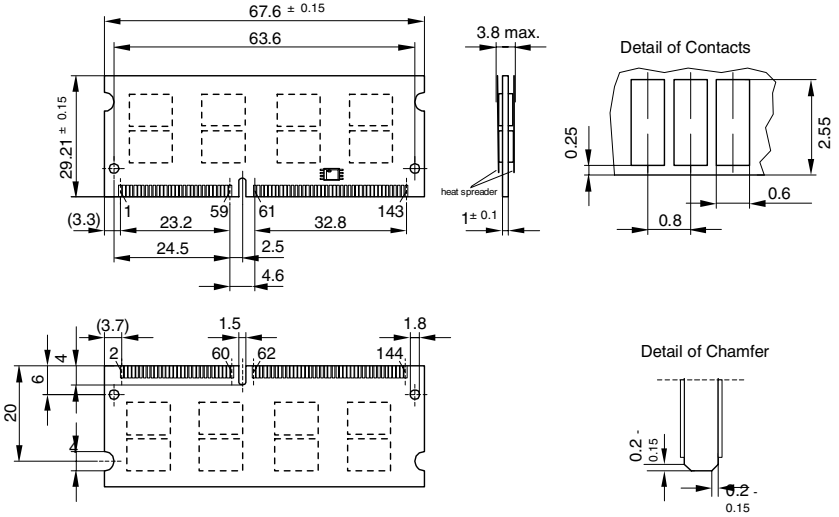
Byte#	Description	SPD Entry Value		Hex	
			64Mx64 -7	64Mx64 -7.5	64Mx64 -8
0	Number of SPD bytes	128	80		
1	Total bytes in Serial PD	256	08		
2	Memory Type	SDRAM	04		
3	Number of Row Addresses (without BS)	12	0D		
4	Number of Column Addresses	10	0A		
5	Number of DIMM Banks	2	02		
6	Module Data Width	64	40		
7	Module Data Width (cont'd)	0	00		
8	Module Interface Levels	LVTTL	01		
9	SDRAM Cycle Time at CL=3	7.5ns / 10.0 ns	75	75	A0
10	SDRAM Access time from Clock at CL=3	5.4ns / 6.0 ns	54	54	60
11	Dimm Config (Error Det/Corr.)	none	00		
12	Refresh Rate/Type	Self-Refresh, 7,6µs	82		
13	SDRAM width, Primary	x8	08		
14	Error Checking SDRAM data width	n/a	00		
15	Minimum clock delay for back-to-back random column address	t_{ccd} = 1 CLK	01		
16	Burst Length supported	1, 2, 4 & 8	0F		
17	Number of SDRAM banks	2	04		
18	Supported CAS Latencies	2, & 3	06		
19	CS Latencies	CS latency = 0	01		
20	WE Latencies	Write latency = 0	01		
21	SDRAM DIMM module attributes	non buffered/non reg.	00		
22	SDRAM Device Attributes :General	VDD tol +/- 10%	0E		
23	SDRAM Cycle Time at CL = 2	7.5ns / 10.0 ns	75	A0	
24	SDRAM Access Time from Clock at CL=2	5.4ns / 6.0 ns	54	60	
25	SDRAM Cycle Time at CL = 1	not supported	00	FF	FF
26	SDRAM Access Time from Clock at CL=1	not supported	00	FF	FF
27	Minimum Row Precharge Time	20 ns	0F	14	

SPD-Table (cont'd):

Byte#	Description	SPD Entry Value	Hex	Hex	Hex
			64Mx64 -7	**64Mx64 -7.5**	**64Mx64 -8**
28	Minimum Row Active to Row Active delay	14/15/16 ns	0E	0F	10
29	Minimum RAS to CAS delay	15/20 ns	0F	14	
30	Minimum Ras pulse width	42/45 ns	2A	2D	32
31	Module Bank Density (per bank)	256 MB		40	
32	SDRAM input setup time	2 ns	15	15	20
33	SDRAM input hold time	1 ns	08	08	10
34	SDRAM data input setup time	2 ns	15	15	20
35	SDRAM data input hold time	1 ns	08	08	10
36-61	Superset information		00	FF	FF
62	SPD Revision	Revision 1.2		12	
63	Checksum for bytes 0 - 62		0E	37	9A
64-125	Manufactures's information (optional)			XX	
126	Frequency Specification	PC100		64	
127	Details			C7	
128+	Unused storage locations		00	FF	FF

Package Outlines

512 MByte SO-DIMM Module package (JEDEC MO-190)
(144 pin, dual in-line memory module)



L-DIM-144-14

Note: All tolerances according to JEDEC standard